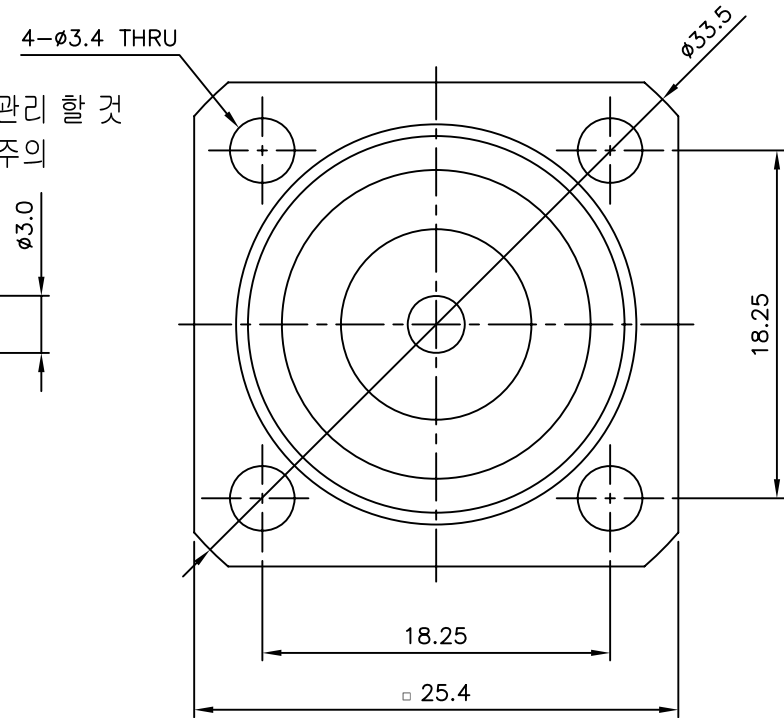
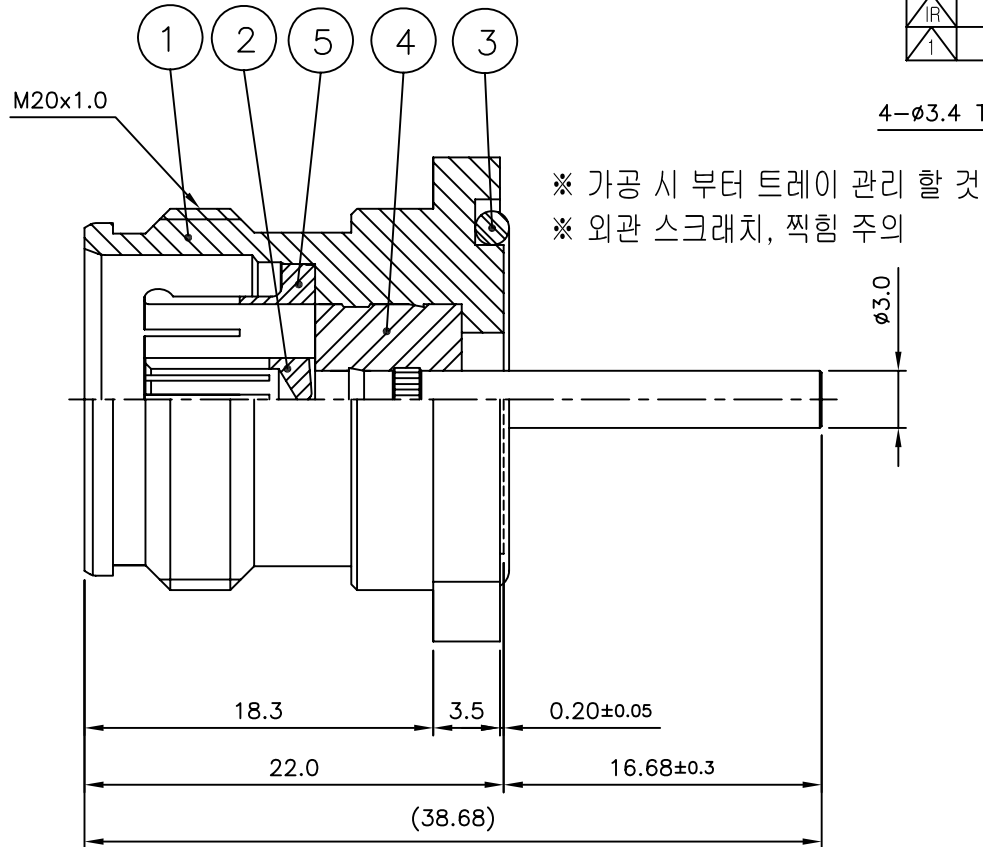
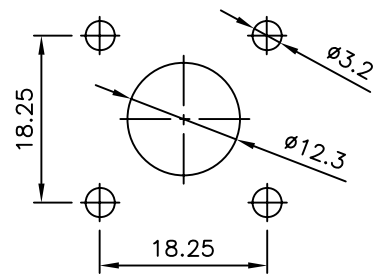


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2017. 09. 13.
↑	[설번처리No. 201907-0004] 절연체 길이 변경	I.C.KIM		2019. 07. 02.



ELECTRICAL DATA

1	Frequency range	DC ~ 6.0 GHz
2	IMPEDANCE	50Ω NOMINAL
3	V.S.W.R	1.2 : 1 max
4	Insertion Loss	-0.2dB min
5	PIMD	160dBc (Min) (20W*2Tone)



MOUNTING HOLE SIZE
(ML17)

* 조립 순서

1. BODY와 절연체 조립
2. 조립한 BODY와 JACK 억지끼움 조립
3. PIN 조립

5	JACK	1	MBsBD C3604BD-F	Silver Plate	DJA00228-5/6
4	INSULATOR	1	TEFLON		DIN02945-N/2 DIN02945-N/1
3	GASKET	1	SILICONE RUB		DGK00179-N/1
2	CONTACT	1	BeCu C17300	Silver Plate (5μm)	DCT03883-5/1
1	BODY	1	MBsBD C3604BD-F	SUCO Plate	DBD04354-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2019. 07. 02.	
	Angle	APPROVED BY	
MATERIAL		CHECKED BY	
		DRAWN BY	I.C.KIM
FINISH		SCALE	UNIT
		2.5/1	mm



RF & MICROWAVE
TECHNOLOGY
Tel : 82-32-347-8015
Fax : 82-32-347-8017

TITLE
4.3-10 SOLDER END JS-4H

A4	DWG NO.	CN03732-7/1
	REVISION	1
	SHEET	1 of 1